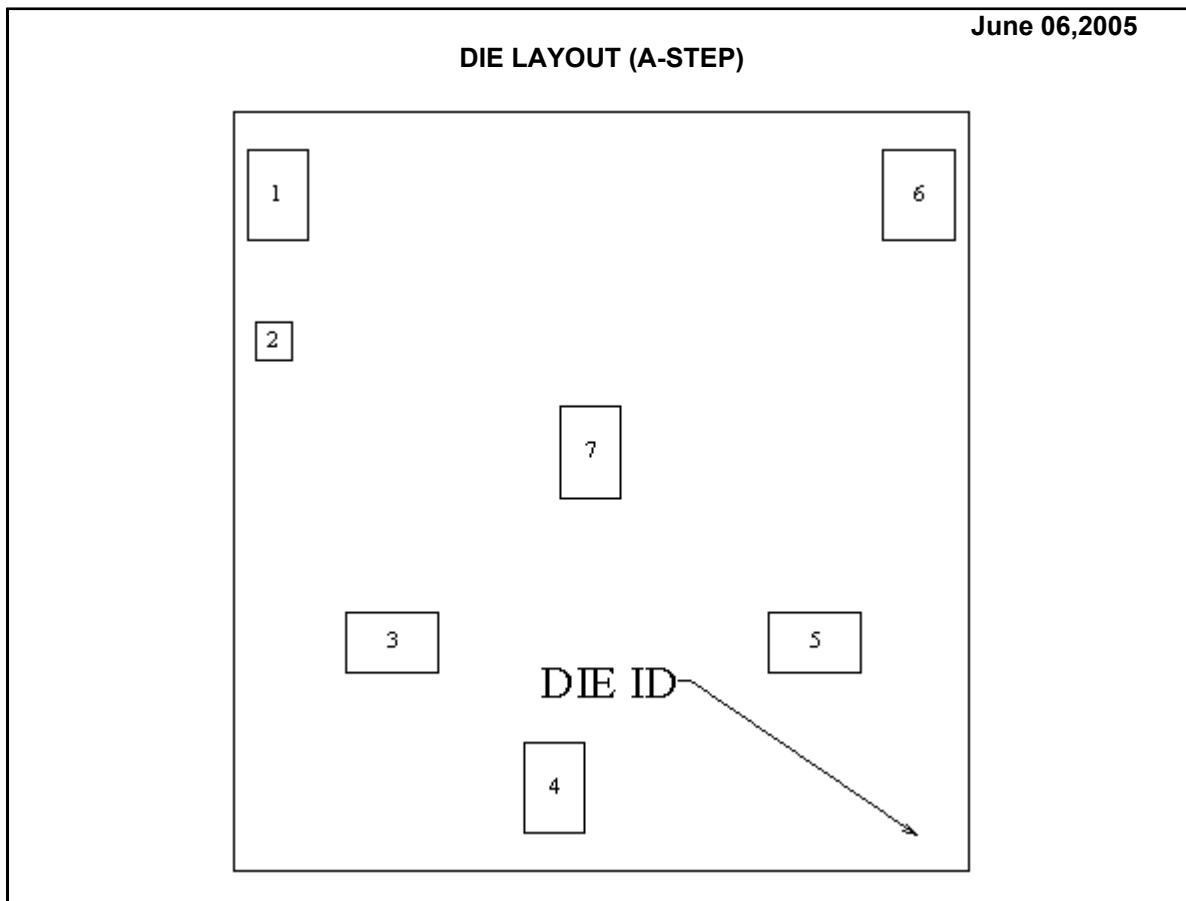


LM350A MDC MWC
3-AMP ADJUSTABLE REGULATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM150A	Bond Pad Opening Size (min)	193μm x 295μm
Die Step	A	Bond Pad Metalization	Al 2%Cu
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TINIAG
Die Size (Drawn)	2362μm x 2438μm 93.0mils x 96.0mils	Back Side Connection	OUTPUT
Thickness	330μm Nominal		
Min Pitch	468μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
ADJ	1	-1041	953	193	x	295
NC	2	-1054	484	117	x	119
OUTPUT	3	-673	-483	295	x	193
VIN	4	-152	-953	193	x	295
OUTPUT	5	686	-483	295	x	193
OUTPUT	6	1022	953	231	x	295
VIN	7	-33	127	193	x	295

LM350A MDC MWC
3-AMP ADJUSTABLE REGULATORS**LIFE SUPPORT POLICY**

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